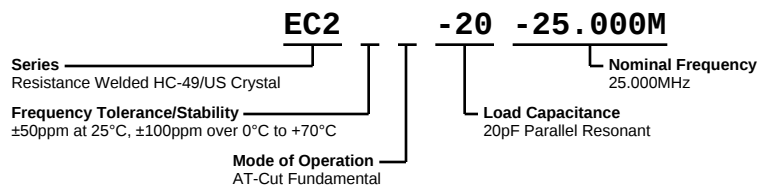


EC2-20-25.000M



ELECTRICAL SPECIFICATIONS

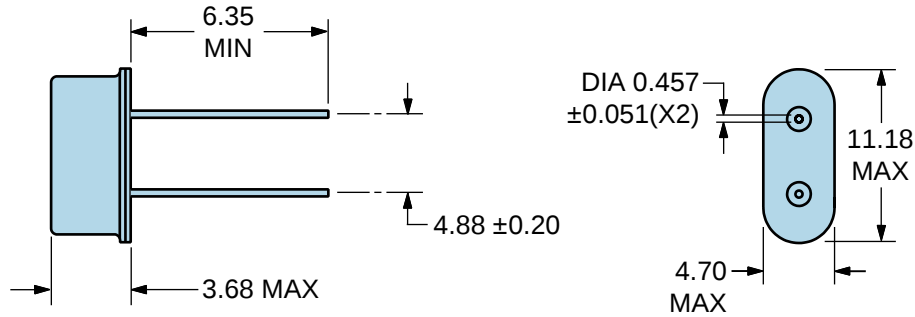
Nominal Frequency	25.000MHz
Frequency Tolerance/Stability	±50ppm at 25°C, ±100ppm over 0°C to +70°C
Aging at 25°C	±5ppm/year Maximum
Load Capacitance	20pF Parallel Resonant
Shunt Capacitance (C0)	7pF Maximum
Equivalent Series Resistance	40 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	1mWatt Maximum
Storage Temperature Range	-40°C to +85°C
Insulation Resistance	500 Megaohms Minimum at 100Vdc

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014 Condition A
Gross Leak Test	MIL-STD-883, Method 1014 Condition C
Lead Integrity	MIL-STD-883, Method 2004
Mechanical Shock	MIL-STD-202, Method 213 Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007 Condition A

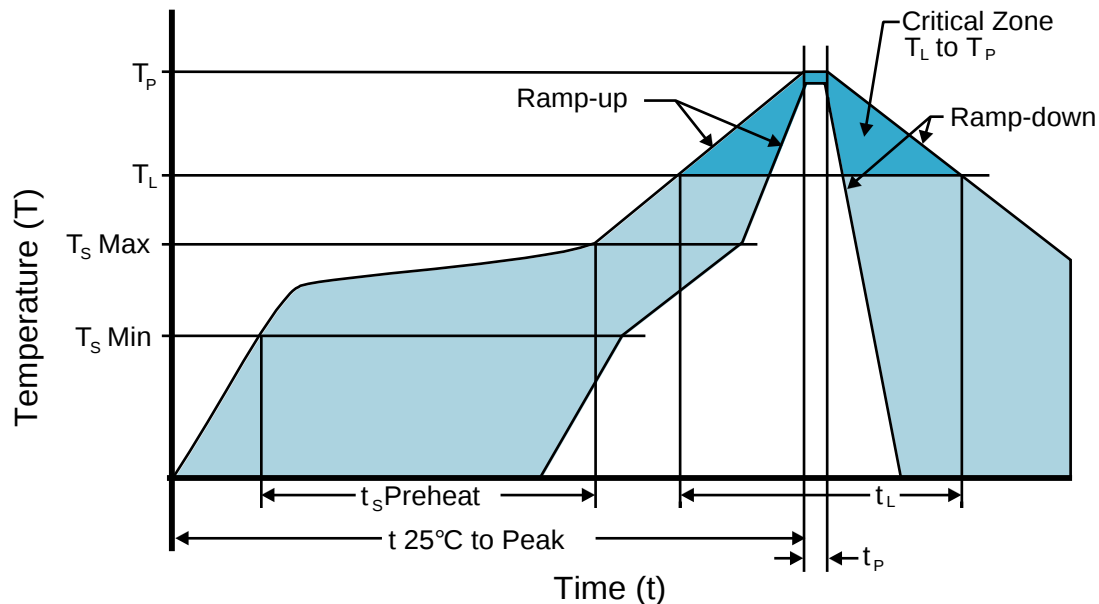
EC2-20-25.000M

MECHANICAL DIMENSIONS (all dimensions in millimeters)



LINE	MARKING
1	E25.000M <i>E=Ecliptek Designator</i> <i>M=Frequency Unit of Measure</i>

Recommended Solder Reflow Methods



High Temperature Solder Bath (Wave Solder)

Ts MAX to TL (Ramp-up Rate) 3°C/second Maximum

Preheat

- Temperature Minimum (Ts MIN) 150°C
- Temperature Typical (Ts TYP) 175°C
- Temperature Maximum (Ts MAX) 200°C
- Time (ts MIN) 60 - 180 Seconds

Ramp-up Rate (TL to Tp) 3°C/second Maximum

Time Maintained Above:

- Temperature (TL) 217°C
- Time (tL) 60 - 150 Seconds

Peak Temperature (Tp) 260°C Maximum for 10 Seconds Maximum

Target Peak Temperature (Tp Target) 250°C +0/-5°C

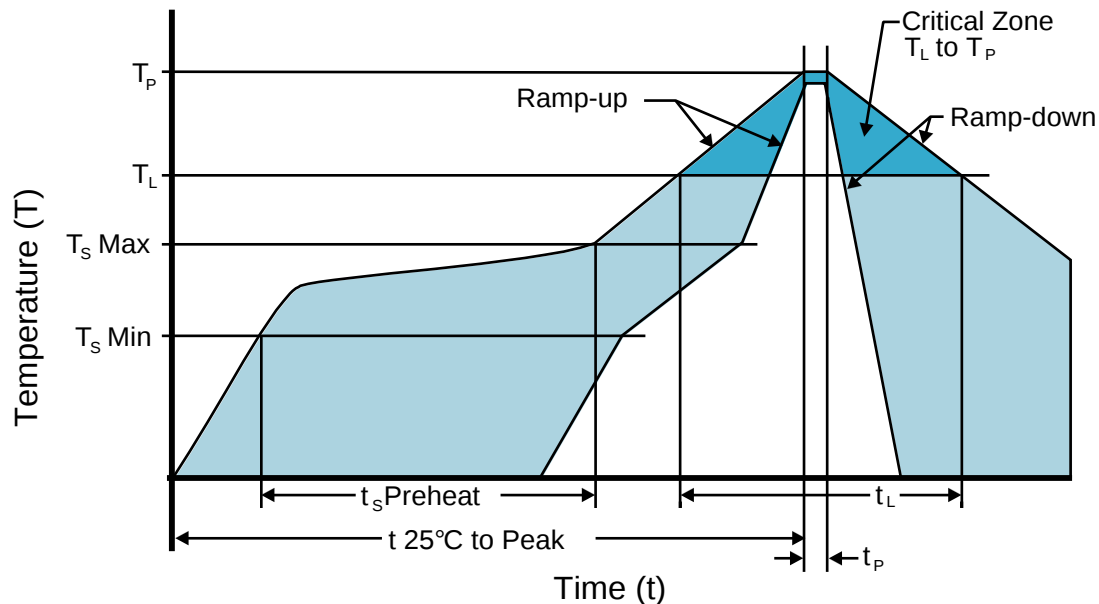
Time within 5°C of actual peak (tp) 20 - 40 seconds

Ramp-down Rate 6°C/second Maximum

Time 25°C to Peak Temperature (t) 8 minutes Maximum

Moisture Sensitivity Level Level 1

Recommended Solder Reflow Methods



Low Temperature Solder Bath (Wave Solder)

T_S MAX to T_L (Ramp-up Rate) 5°C/second Maximum

Preheat

- Temperature Minimum (T_S MIN) N/A
- Temperature Typical (T_S TYP) 150°C
- Temperature Maximum (T_S MAX) N/A
- Time (t_S MIN) 30 - 60 Seconds

Ramp-up Rate (T_L to T_P) 5°C/second Maximum

Time Maintained Above:

- Temperature (T_L) 150°C
- Time (t_L) 200 Seconds Maximum

Peak Temperature (T_P) 245°C Maximum

Target Peak Temperature (T_P Target) 245°C Maximum 1 Time / 235°C Maximum 2 Times

Time within 5°C of actual peak (t_P) 5 seconds Maximum 1 Time / 15 seconds Maximum 2 Times

Ramp-down Rate 5°C/second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.